

Using the TPS22945EVM-082 Single Channel Current Limited Load Switch IC

The TPS22945EVM-082 evaluation module (EVM) allows the user to connect power to and control the 5pin DCK package load switch. The features of the current limiting switch can be easily evaluated using the EVM connections. Table 1 lists a short description of the TPS22945 load switch performance specifications; for additional details on load switch performance, application notes, and the datasheet see ti.com/loadswitch.

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Introduction

1 Introduction

EVN	1	Device	Current Limit Minimum	Current Limit Blanking Time	Auto Restart Time	Enable (ON Pin)
HVL0	32 TI	PS22945	100 mA	10 ms	80 ms	Active High

1.1 Description

The TPS22945EVM is a two sided PCB containing the TPS22945 load switch device. The VIN and VOUT connections to the device and the PCB layout routing provide a low resistance pathway into and out of the device under test. Test point connections allow the EVM User to control the device with user defined test conditions and make accurate R_{ON} and timing measurements.

1.2 Features

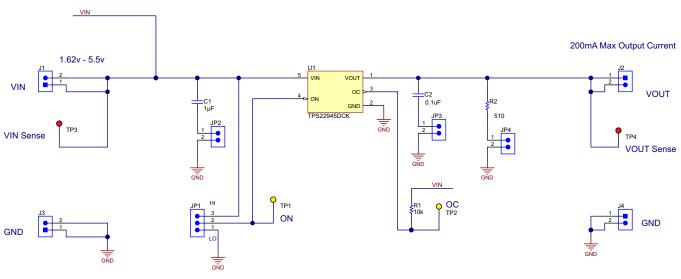
- VIN input voltage range: 1.62 V to 5.5 V.
- EVM allows access to the VIN, VOUT, GND, ON and OC pin of the TPS22945 Load Switch Device.
- On board C_{IN} and C_{OUT} capacitors.
- VIN Sense and VOUT Sense test points provide an accurate measurement point of contact to the device.

2 Electrical Performance

Refer to the datasheet for detailed electrical characteristics of the TPS22945 (SLVS832).

3 Schematic

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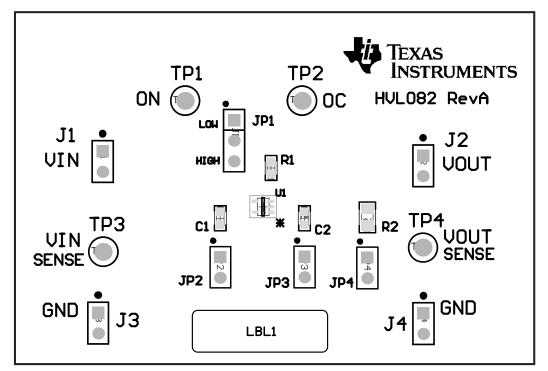


Figure 2. TPS22945EVM-082 Top Assembly

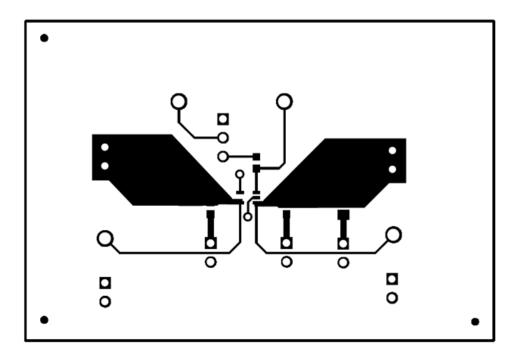


Figure 3. TPS22945EVM-082 Top Layout



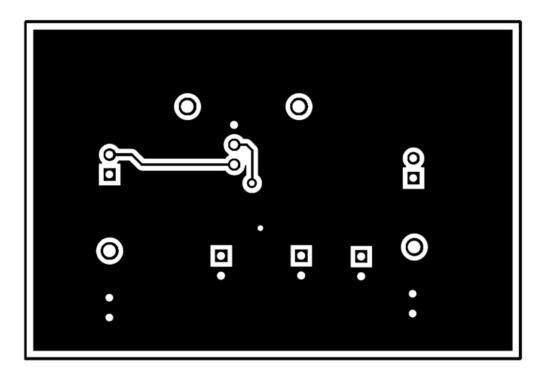


Figure 4. TPS22945EVM-082 Bottom Layout

4.1 Setup

This section describes the jumpers and connectors on the EVM as well as how to properly connect, set up, and use the EVM.

4.1.1 J1 – VIN Connection

This is the connection for the positive lead from the input source

4.1.2 J2 – VOUT Connection

This is the connection point for the output of the device.

4.1.3 JP1 - ON

This is the enable input for the device. A shorting jumper must be installed on JP1 in either the High or Low position. The TPS22945 is active High. ON must not be left floating. An external enable source can be applied to the EVM by removing the shunt and connecting a signal to TP1. Refer to the datasheet for proper ON and OFF voltage level settings. A switching signal may also be used and connected at this point.

TP3 - VIN Sense, TP4 - VOUT Sense 4.1.4

These two connections are used when very accurate measurements of the input or output are required. RON measurements should be made using these sense connections when measuring the voltage drop from VIN to VOUT to calculate the resistance.

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4.1.5 JP2 - Input Capacitor

During normal operation a shorting jumper is placed on JP2 this connects C1 capacitor from the input of the device to ground. Refer to the Applications Section of the datasheet for additional information on selecting the input capacitor.

4.1.6 JP3 - Output Capacitor

During normal operation a shorting jumper is placed on JP3 this connects C2 capacitor from the output of the device to ground. Refer to the Applications Section of the datasheet for additional information on selecting the output capacitor.

4.1.7 J3 – J4– GND

These are connections to GND.

5 Operation

Connect the positive input of the VIN power supply to VIN at J1. Connect the negative lead of the power supply to GND at J3. The input voltage range of the TPS22945EVM-082 is 1.62 V to 5.5 V.

External output loads can be applied to the switch by using J2 VOUT and J4 GND. Configure JP1 as required. JP1 must be installed for proper operation. When the ON pin is asserted high, the output of the TPS22945 will be enabled.

6 Test Configurations

6.1 On-Resistance (R_{ON}) Test Setup

Figure 5 shows a typical setup for measuring On-Resistance. The voltage drop across the switch is measured using the sense connections then divided by the current into the load yielding the RON resistance.

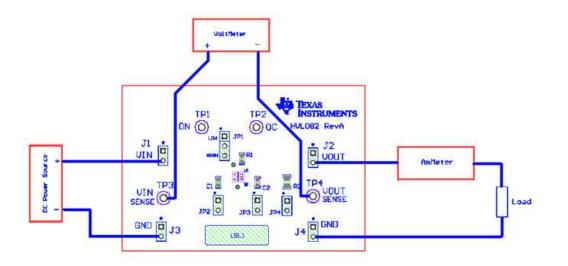


Figure 5. R_{ON} Setup

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Test Configurations

6.2 Timing Test Setup

Figure 6 shows a test setup for measuring some of the typical timing features of the TPS22945 load switch. The OC output pin will switch to a low state when an overload condition or other fault conditions are encountered by the device. Connecting the switch as shown below will allow the user to capture these fault conditions with an oscilloscope.

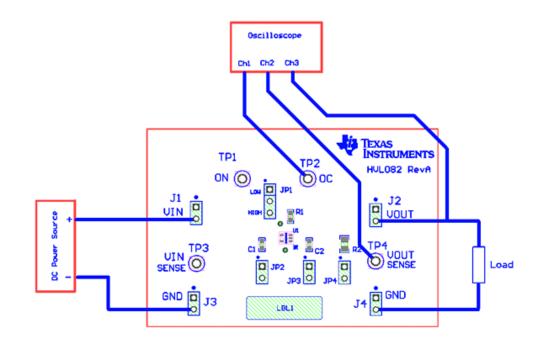
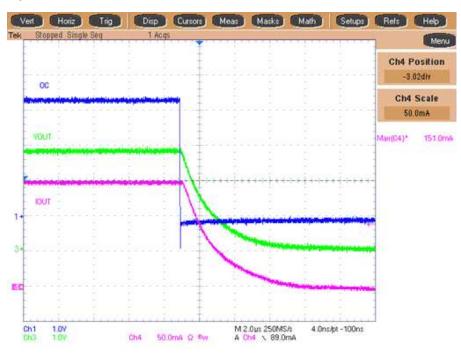


Figure 6. Typical Timing Setup



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6.3 Some Examples of TPS22945 Fault Detection Conditions

Figure 7. TPS22945 Over Current Shutdown (V_{IN} = 3.3V)



Figure 8. TPS22945 Operating in Constant Current Mode with Auto Restart (V_{IN} = 3.3V)



Bill of Materials (BOM)

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7 Bill of Materials (BOM)

Qty	Value	Description	Package Reference	Part Number	Manufacturer
1		Printed Circuit Board		HVL082	Any
1	1μF	CAP, CERM, 1µF, 25V, ±10%, X7R, 0603	0603	GRM188R71E105KA12D	Murata
1	0.1µF	CAP, CERM, 0.1µF, 100V, ±10%, X7R, 0603	0603	GRM188R72A104KA35D	Murata
3		Fiducial mark. There is nothing to buy or mount.	Fiducial	N/A	N/A
4		Header, 100mil, 2x1, Gold, TH	Header, 2x1, 100mil	5-146261-1	TE Connectivity
1		Header, 100mil, 3x1, Tin plated, TH	Header, 3 PIN, 100mil, Tin	PEC03SAAN	Sullins Connector Solutions
3		Header, 100mil, 2x1, Tin plated, TH	Header, 2 PIN, 100mil, Tin	PEC02SAAN	Sullins Connector Solutions
1		Thermal Transfer Printable Labels, 0.650" W x 0.200" H - 10,000 per roll	PCB Label 0.650"H x 0.200"W	THT-14-423-10	Brady
1	10k	RES, 10kΩ, 5%, 0.1W, 0603	0603	CRCW060310K0JNEA	Vishay-Dale
1	510	RES, 510 Ω, 5%, 0.125W, 0805	0805	ERJ-6GEYJ511V	Panasonic
2	Yellow	Test Point, Multipurpose, Yellow, TH	Yellow Multipurpose Testpoint	5014	Keystone
2	Red	Test Point, Multipurpose, Red, TH	Red Multipurpose Testpoint	5010	Keystone
1		Low-input-voltage current-limited load switches with shut off and auto-restart feature, DCK0005A	DCK0005A	TPS22945DCK	Texas Instruments
	1 1 3 4 1 3 1 1 1 1 2	$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	1 Printed Circuit Board 1 μ F CAP, CERM, 1μ F, 25V, $\pm 10\%$, X7R, 0603 1 0.1μ F CAP, CERM, 0.1μ F, 100V, $\pm 10\%$, X7R, 0603 3 Fiducial mark. There is nothing to buy or mount. 4 Header, 100mil, 2x1, Gold, TH 1 Header, 100mil, 2x1, Gold, TH 3 Header, 100mil, 2x1, Tin plated, TH 1 Header, 100mil, 2x1, Tin plated, TH 1 Thermal Transfer Printable Labels, 0.650" W x 0.200" H - 10,000 per roll 1 10k RES, 10k\Omega, 5%, 0.1W, 0603 1 510 RES, 510 \Omega, 5%, 0.125W, 0805 2 Yellow Test Point, Multipurpose, Yellow, TH 2 Red Test Point, Multipurpose, Red, TH 1 Low-input-voltage current-limited load switches with shut	1 Printed Circuit Board 1 1µF CAP, CERM, 1µF, 25V, ±10%, X7R, 0603 0603 1 0.1µF CAP, CERM, 0.1µF, 100V, ±10%, X7R, 0603 0603 3 Fiducial mark. There is nothing to buy or mount. Fiducial 4 Header, 100mil, 2x1, Gold, TH Header, 2x1, 100mil 1 Header, 100mil, 2x1, Gold, TH Header, 3 PIN, 100mil, Tin 1 Header, 100mil, 2x1, Tin plated, TH Header, 2 PIN, 100mil, Tin 1 Header, 100mil, 2x1, Tin plated, TH Header, 2 PIN, 100mil, Tin 1 Thermal Transfer Printable Labels, 0.650" W x 0.200" H - 10,000 per roll 0.650"H x 0.200"W 1 10k RES, 10kΩ, 5%, 0.1W, 0603 0603 1 510 RES, 510 Ω, 5%, 0.125W, 0805 0805 2 Yellow Test Point, Multipurpose, Yellow, TH Yellow Multipurpose Testpoint Yellow Multipurpose Testpoint 2 Red Test Point, Multipurpose, Red, TH Red Multipurpose Testpoint	1 Printed Circuit Board HVL082 1 1µF CAP, CERM, 1µF, 25V, ±10%, X7R, 0603 0603 GRM188R71E105KA12D 1 0.1µF CAP, CERM, 0.1µF, 100V, ±10%, X7R, 0603 0603 GRM188R72A104KA35D 3 Fiducial mark. There is nothing to buy or mount. Fiducial N/A 4 Header, 100mil, 2x1, Gold, TH Header, 2x1, 100mil 5-146261-1 1 Header, 100mil, 2x1, Gold, TH Header, 3 PIN, 100mil, Tin PEC03SAAN 3 Header, 100mil, 2x1, Tin plated, TH Header, 2 PIN, 100mil, Tin PEC02SAAN 1 Thermal Transfer Printable Labels, 0.650" W x 0.200" H - 10,000 per roll 0.650"H x 0.200"W THT-14-423-10 1 10k RES, 510 Ω, 5%, 0.1W, 0603 0603 CRCW060310K0JNEA 1 510 RES, 510 Ω, 5%, 0.125W, 0805 0805 ERJ-6GEYJ511V 2 Yellow Test Point, Multipurpose, Yellow, TH Yellow Multipurpose Testpoint 5010 2 Red Test Point, Multipurpose, Red, TH Red Multipurpose Testpoint 5010 1 Low-input-voltage current-limited load switches with shut

Table 2. TPS22945EVM-082 Bill of Materials

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